

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A diode 2 comprising a connecting means 6 and a heat sink base 7;

 said connecting means 6 comprising a flat end 5 fixed at a die 16 and the other end having no fixed shape;

 said heat sink base 7 comprising;

 a base 18 which is on the bottom of the heat sink base 7;

 a press-fit region 4 which is around said base 18;

 a solder platform which is above said base 18;

 a die 16 which has a first side and a second side electrically coupled to said flat end 5 and said solder platform 17, respectively;

 a shoulder 12 which is extended acclivitously from said solder platform 17, the root of said shoulder 12 connected to said solder platform 17; and

 a cup 14 which is extended upwardly from the periphery of said base 18;

 characterized in that said solder platform 17 has an anchor mechanism 11 equipped with said acclivitous shoulder 12 and a kink 13, and that the combination of

~~said acclivitous shoulder 12 and said kink 13~~ said mechanism can absorb the stress generated by the epoxy package 8 and provide a longer path for moisture to reach the die 16, thereby preventing moisture from reaching the die 16 directly even if moisture enters the gap ~~existing~~ existing between the shoulder 12 and the passivative material film 10.

Claim 2 (original). The diode 2 of Claim 1, wherein said shoulder 12 has a height which is substantially the same as said die 16.

Claim 3 (original). The diode 2 of Claim 1, wherein said connecting means 6 is a lead wire.

Claim 4 (original). The diode 2 of Claim 1, further comprises two solder layers 15a and 15b which sandwich said die 16 above and under, respectively.

Claim 5 (currently amended). The diode 2 of Claim 4, further comprises passivative material film 10 used to surround said wafer 16.

Claim 6 (currently amended). The diode 2 of Claim 5, further comprises an epoxy 8 for surrounding outside said passivative material film 10.

Claim 7 (currently amended). The diode 2 of Claim 6, further comprises a sheath 20 for surrounding said epoxy package 8 inside said cup 14.

Claim 8 (currently amended). The diode 2 of Claim 6, further comprises a sheath 20 for surrounding said epoxy package 8 outside said cup 14.